

SNx4AHCT573 3 ステート出力、オクタートランスペアレント D タイプ ラッチ

1 特長

- 入力は TTL 電圧互換
- JESD 17 準拠で 250mA 超のラッチアップ性能
- MIL-PRF-38535 準拠の製品については、特に記述のない限り、すべてのパラメータはテスト済みです。
その他のすべての製品については、量産プロセスにすべてのパラメータのテストが含まれているとは限りません。

2 アプリケーション

- サーバー
- PC およびノートパソコン
- ネットワーク スイッチ
- ウェアラブルなヘルスケア / フィットネス機器
- テレコム インフラストラクチャ
- レジ用電子機器

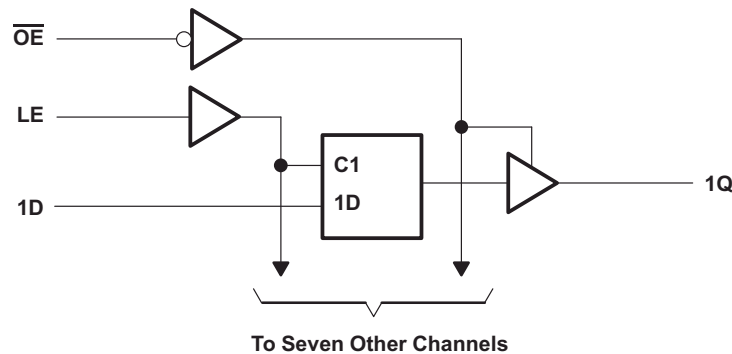
3 概要

SNx4AHCT573 デバイスはオクタール トランスペアレント D タイプ ラッチです。ラッチ イネーブル (LE) 入力が HIGH の場合、Q 出力はデータ (D) 入力に従います。LE を LOW にすると、D 入力のロジックレベルで Q 出力がラッチされます。

製品情報

部品番号	定格 ⁽¹⁾	パッケージ ⁽¹⁾
SN74AHCT573	カタログ	DB (SSOP, 20)
		DGV (TVSOP, 20)
		DW (SOIC, 20)
		N (PDIP, 20)
		PW (TSSOP, 20)
SN54AHCT573	軍用	J (CDIP, 20)
		W (CFP, 20)

(1) 詳細については、[セクション 11](#) を参照してください。



概略回路図



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4 Pin Configuration and Functions

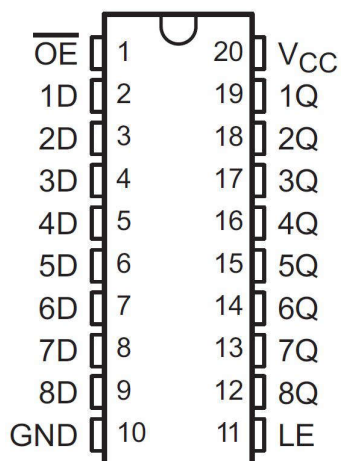


図 4-1. SN54AHCT573 J or W Package
SN74AHCT573 DB, DGV, DW, N, NS, or PW
Package (Top View)

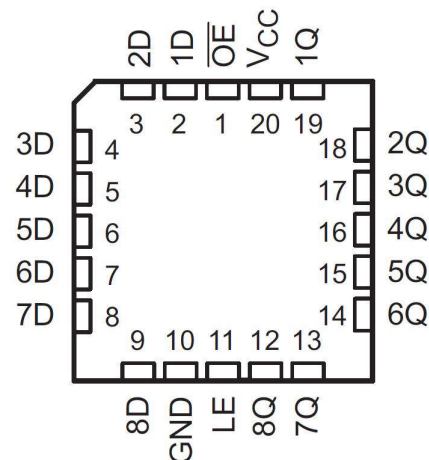


図 4-2. SN54AHCT573 FK Package (Top View)

表 4-1. Pin Functions

PIN		TYPE ⁽¹⁾	DESCRIPTION
NO.	NAME		
1	OE	I	Output Enable
2	1D	I	1D Input
3	2D	I	2D Input
4	3D	I	3D Input
5	4D	I	4D Input
6	5D	I	5D Input
7	6D	I	6D Input
8	7D	I	7D Input
9	8D	I	8D Input
10	GND	—	Ground
11	LE	I	Latch Enable
12	8Q	O	8Q Output
13	7Q	O	7Q Output
14	6Q	O	6Q Output
15	5Q	O	5Q Output
16	4Q	O	4Q Output
17	3Q	O	3Q Output
18	2Q	O	2Q Output
19	1Q	O	1Q Output
20	V _{CC}	—	Power Pin

(1) I = input, O = output

5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		MIN	MAX	UNIT
V _{CC}	Supply voltage range	−0.5	7	V
V _I	Input voltage range ⁽²⁾	−0.5	7	V
V _O	Output voltage range ⁽²⁾	−0.5	V _{CC} + 0.5	V
I _{IK}	Input clamp current	V _I < 0		−20 mA
I _{OK}	Output clamp current	V _O < 0 or V _O > V _{CC}		±20 mA
I _O	Continuous output current	V _O = 0 to V _{CC}		±25 mA
	Continuous current through V _{CC} or GND			±75 mA
T _J	Junction temperature			150 °C
T _{stg}	Storage temperature	−65		150 °C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

5.2 ESD Ratings

			MIN	MAX	UNIT
V _(ESD)	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾		±2000	V
		Charged-device model (CDM), per ANSI/ESDA/JEDEC JS-002 ⁽²⁾		±1000	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

5.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		SN54AHCT573		SN74AHCT573		UNIT
		MIN	MAX	MIN	MAX	
V _{CC}	Supply voltage	4.5	5.5	4.5	5.5	V
V _{IH}	High-level input voltage	2		2		V
V _{IL}	Low-level input voltage		0.8		0.8	V
V _I	Input voltage	0	5.5	0	5.5	V
V _O	Output voltage	0	V _{CC}	0	V _{CC}	V
I _{OH}	High-level output current		−8		−8	mA
I _{OL}	Low-level output current		8		8	mA
Δt/Δv	Input transition rise or fall rate		20		20	ns/V
T _A	Operating free-air temperature	−55	125	−40	125	°C

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs* (SCBA004).

5.4 Thermal Information

THERMAL METRIC ⁽¹⁾		SN74AHCT573						UNIT
		DW	DB	DGV	N	NS	PW	
		20 PINS						
R _{θJA}	Junction-to-ambient thermal resistance	79.4	97.9	117.2	53.3	79.2	116.8	°C/W
R _{θJC(top)}	Junction-to-case (top) thermal resistance	45.7	59.6	32.7	40.0	45.7	58.5	
R _{θJB}	Junction-to-board thermal resistance	46.9	53.1	58.7	34.2	46.8	78.7	
Ψ _{JT}	Junction-to-top characterization parameter	18.7	21.3	1.15	26.4	19.3	12.6	
Ψ _{JB}	Junction-to-board characterization parameter	46.5	52.7	58.0	34.1	46.4	77.9	
R _{θJC(bot)}	Junction-to-case (bottom) thermal resistance	N/A	N/A	N/A	N/A	N/A	N/A	

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report ([SPRA953](#)).

5.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	T _A = 25°C			–55°C to 125°C SN54AHCT573		–40°C to 85°C SN74AHCT573		–40°C to 125°C SN74AHCT573		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
V _{OH}	I _{OH} = –50 μA	4.5V	4.4	4.5		4.4		4.4		4.4		V
	I _{OH} = –8mA		3.94			3.8		3.8		3.8		
V _{OL}	I _{OL} = 50 μA	4.5V			0.1		0.1		0.1		0.1	V
	I _{OL} = 8mA				0.36		0.44		0.44		0.44	
I _I	V _I = 5.5V or GND	0V to 5.5V			±0.1		±1 ⁽¹⁾		±1		±2	μA
I _{OZ}	V _O = V _{CC} or GND	5.5V			±0.25		±2.5		±2.5		±2.5	μA
I _{CC}	V _I = V _{CC} or GND, I _O = 0	5.5V			4		40		40		40	μA
ΔI _{CC} ⁽²⁾	One input at 3.4V, Other inputs at V _{CC} or GND	5.5V			1.35		1.5		1.5		1.5	mA
C _i	V _I = V _{CC} or GND	5V		2.5	10				10		10	pF
C _o	V _O = V _{CC} or GND	5V		3								pF

(1) On products compliant to MIL-PRF-38535, this parameter is not production tested at V_{CC} = 0V.

(2) This is the increase in supply current for each input at one of the specified TTL voltage levels, rather than 0V or V_{CC}.

5.6 Timing Requirements

over recommended operating free-air temperature range, V_{CC} = 5V ± 0.5V (unless otherwise noted) (see [セクション 6](#))

PARAMETER		T _A = 25°C		–55°C to 125°C SN54AHCT573		–40°C to 85°C SN74AHCT573		–40°C to 125°C SN74AHCT573		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t _w	Pulse duration, LE high	5		5		5		5		ns
t _{su}	Setup time, data before LE↓	3.5		3.5		3.5		3.5		ns
t _h	Hold time, data after LE↓	1.5		1.5		1.5		1.5		ns

5.7 Switching Characteristics, SNx4AHCT573

over recommended operating free-air temperature range, $V_{CC} = 5V \pm 0.5V$ (unless otherwise noted) (see [セクション 6](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T _A = 25°C		T _A = -40°C to 85°C		T _A = -40°C to 125°C		UNIT	
			MIN	TYP	MAX	MIN	MAX	MIN		MAX
C _L = 15pF										
t _{pd}	D	Q		5.1	7	1	9	1	9.5	ns
t _{pd}	LE	Q		5.6	7.5	1	9	1	9.5	ns
t _{en}	$\overline{\text{OE}}$	Q		5.5	7.5	1	10	1	11	ns
t _{dis}	$\overline{\text{OE}}$	Q		5.5	8	1	11	1	12	ns
C _L = 50pF										
t _{pd}	D	Q		6.1	8	1	10	1	10.5	ns
t _{pd}	LE	Q		6.6	8.5	1	10	1	10.5	ns
t _{en}	$\overline{\text{OE}}$	Q		6.5	8.5	1	11	1	11.5	ns
t _{dis}	$\overline{\text{OE}}$	Q		6.7	9	1	12	1	12.5	ns
t _{sk(o)}					1.5		1.5			ns

- (1) On products compliant to MIL-PRF-38535, this parameter is not production tested.
(2) On products compliant to MIL-PRF-38535, this parameter does not apply.

5.8 Switching Characteristics, SN54AHCT573

over recommended operating free-air temperature range, $V_{CC} = 5V \pm 0.5V$ (unless otherwise noted) (see [セクション 6](#))

For recommended operating conditions, T_A = 25°C (unless otherwise noted)								
PARAMETER	FROM (INPUT)	TO (OUTPUT)	$T_A = 25^\circ\text{C}$			$T_A = -55^\circ\text{C to } 125^\circ\text{C}$		UNIT
			MIN	TYP	MAX	MIN	MAX	
$C_L = 15\text{pF}$								
t_{pd}	D	Q		5.1 ⁽¹⁾	7 ⁽¹⁾	1 ⁽¹⁾	9 ⁽¹⁾	ns
t_{pd}	LE	Q		5.6 ⁽¹⁾	7.5 ⁽¹⁾	1 ⁽¹⁾	9 ⁽¹⁾	ns
t_{en}	$\overline{OE}$	Q		5.5 ⁽¹⁾	7.5 ⁽¹⁾	1 ⁽¹⁾	9 ⁽¹⁾	ns
t_{dis}	$\overline{OE}$	Q		5.5 ⁽¹⁾	8 ⁽¹⁾	1 ⁽¹⁾	11 ⁽¹⁾	ns
$C_L = 50\text{pF}$								
t_{pd}	D	Q		6.1	8	1	10	ns
t_{pd}	LE	Q		6.6	8.5	1	10	ns
t_{en}	$\overline{OE}$	Q		6.5	8.5	1	11	ns
t_{dis}	$\overline{OE}$	Q		6.7	9	1	12	ns
$t_{sk(o)}$					1.5 ⁽²⁾			ns

5.9 Operating Characteristics

$V_{CC} = 5V$, $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS		TYP	UNIT
C_{pd}	Power dissipation capacitance	No load,	$f = 1\text{MHz}$	16	pF

5.10 Typical Characteristics

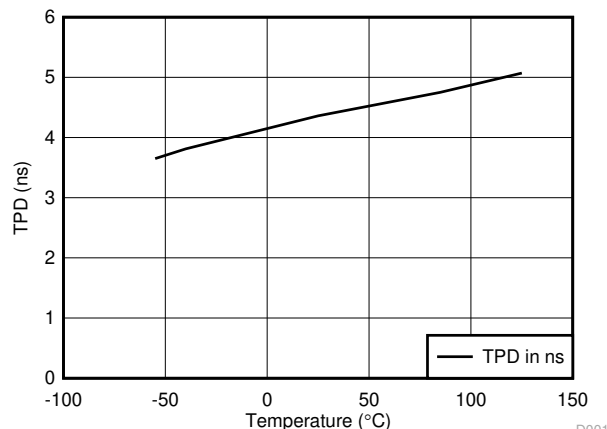


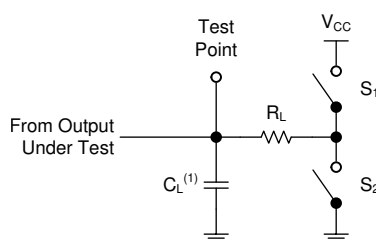
FIG 5-1. TPD vs Temperature at 5V

6 Parameter Measurement Information

Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1\text{MHz}$, $Z_O = 50\Omega$, $R_L = 1\text{k}\Omega$, $t_t < 3\text{ns}$, $V_t = 1.5\text{V}$.

For clock inputs, f_{max} is measured when the input duty cycle is 50%.

The outputs are measured one at a time with one input transition per measurement.



(1) C_L includes probe and test-fixture capacitance.

FIG 6-1. Load Circuit for 3-State Outputs

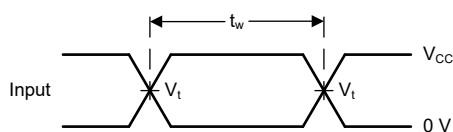


FIG 6-2. Voltage Waveforms, Pulse Duration

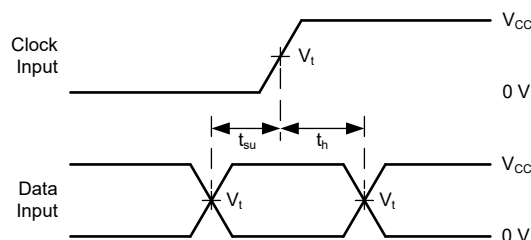
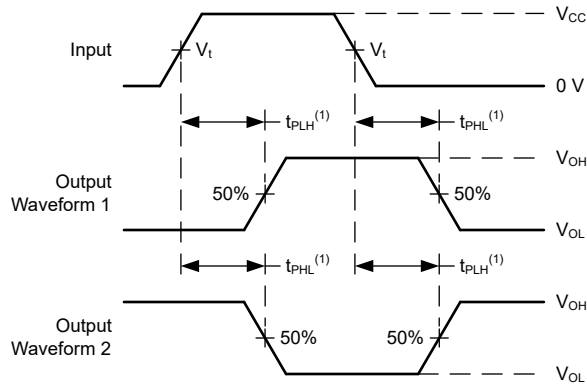
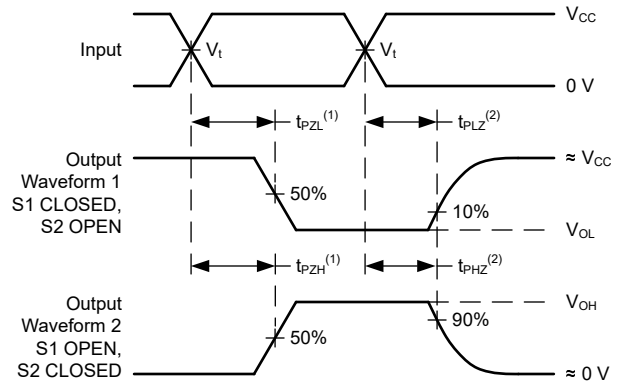


FIG 6-3. Voltage Waveforms, Setup and Hold Times



(1) The greater between t_{PLH} and t_{PHL} is the same as t_{pd} .

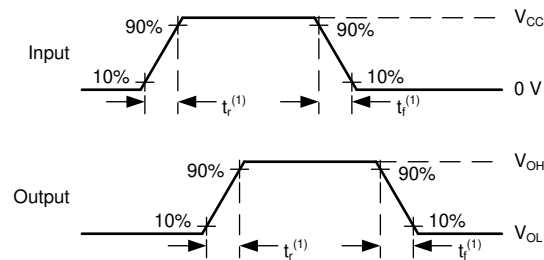
図 6-4. Voltage Waveforms, Propagation Delays



(1) t_{PLZ} and t_{PHZ} are the same as t_{dis} .

(2) t_{PZL} and t_{PZH} are the same as t_{en} .

図 6-5. Voltage Waveforms, Propagation Delays for 3-State Outputs



(1) The greater between t_r and t_f is the same as t_t .

図 6-6. Voltage Waveforms, Input and Output Transition Times

7 Detailed Description

7.1 Overview

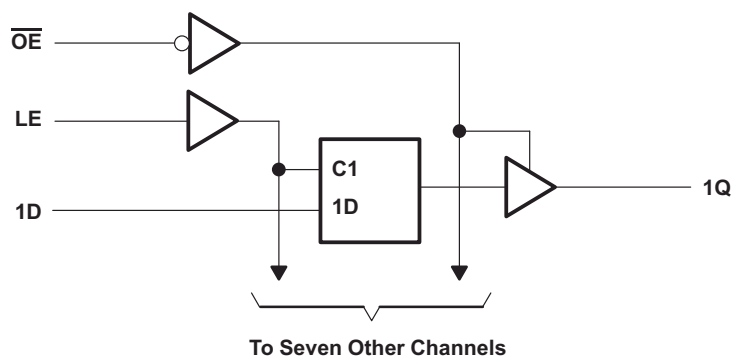
The SNx4AHCT573 devices are octal transparent D-type latches. When the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is low, the Q outputs are latched at the logic levels of the D inputs.

A buffered output-enable ($\overline{OE}$) input can be used to place the eight outputs in either a normal logic state (high or low) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pull-up components.

To put the device in the high-impedance state during power up or power down, tie $\overline{OE}$ to V_{CC} through a pull-up resistor; the current-sinking capability of the driver determines the minimum value of the resistor.

$\overline{OE}$ does not affect the internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

7.2 Functional Block Diagram



7.3 Feature Description

- TTL inputs
 - Lowered switching threshold allows up translation 3.3V to 5V
- Slow edges reduce output ringing

7.4 Device Functional Modes

表 7-1. Function Table
(Each Latch)

INPUTS			OUTPUT Q
OE	LE	D	
L	H	H	H
L	H	L	L
L	L	X	Q ₀
H	X	X	Z

8 Application and Implementation

注

以下のアプリケーション情報は、TI の製品仕様に含まれるものではなく、TI ではその正確性または完全性を保証いたしません。個々の目的に対する製品の適合性については、お客様の責任で判断していただくことになります。お客様は自身の設計実装を検証しテストすることで、システムの機能を確認する必要があります。

8.1 Application Information

The SN74AHCT573 is a low-drive CMOS device that can be used for a multitude of bus interface type applications where output ringing is a concern. The low drive and slow edge rates will minimize overshoot and undershoot on the outputs. The input switching levels have been lowered to accommodate TTL inputs of $0.8V_{IL}$ and $2V_{IH}$. This feature makes the device an excellent choice for translating up from 3.3V to 5V. [図 8-2](#) shows this type of translation.

8.2 Typical Application

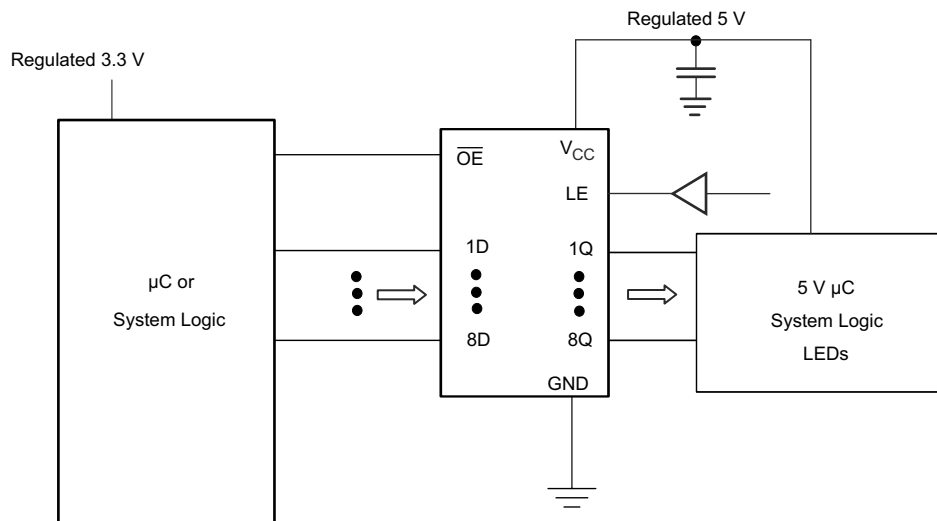


図 8-1. Typical Application Schematic

8.2.1 Design Requirements

This device uses CMOS technology and has balanced output drive. Take care to avoid bus contention because it can drive currents that would exceed maximum limits. The high drive will also create fast edges into light loads; therefore, routing and load conditions should be considered to prevent ringing.

8.2.2 Detailed Design Procedure

- Recommended input conditions:
 - Rise time and fall time specs: See $(\Delta t/\Delta V)$ in the [Recommended Operating Conditions](#) table.
 - Specified High and low levels: See $(V_{IH}$ and $V_{IL})$ in the [Recommended Operating Conditions](#) table.
 - Inputs are overvoltage tolerant allowing them to go as high as 5.5V at any valid V_{CC} .
- Recommend output conditions
 - Load currents should not exceed 25mA per output and 75mA total for the part.
 - Outputs should not be pulled above V_{CC} .

8.2.3 Application Curves

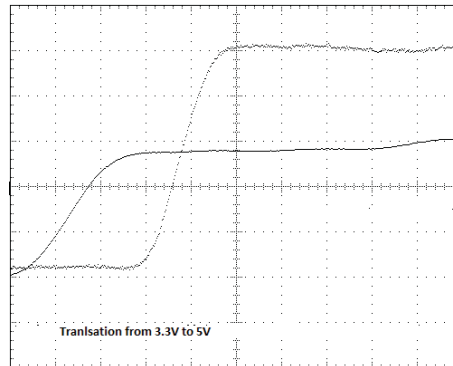


図 8-2. Up Translation

8.3 Power Supply Recommendations

The power supply can be any voltage between the MIN and MAX supply voltage rating located in the [Recommended Operating Conditions](#) table.

Each V_{CC} pin should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, 0.1 μ F bypass capacitor is recommended. If there are multiple V_{CC} pins, 0.01 μ F or 0.022 μ F is recommended for each power pin. It is acceptable to parallel multiple bypass capacitors to reject different frequencies of noise. A 0.1 μ F and 1 μ F are commonly used in parallel. The bypass capacitor should be installed as close to the power pin as possible for best results.

8.4 Layout

8.4.1 Layout Guidelines

When using multiple bit logic devices inputs should never float.

In many cases, functions or parts of functions of digital logic devices are unused (for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used). Such input pins should not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. 図 8-3 specifies the rules that must be observed under all circumstances.

All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that should be applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or V_{CC} ; whichever makes more sense or is more convenient. It is generally acceptable to float outputs unless the part is a transceiver. If the transceiver has an output enable pin, then it will disable the outputs section of the part when asserted. This will not disable the input section of the IOs so they cannot float when disabled.

8.4.2 Layout Example

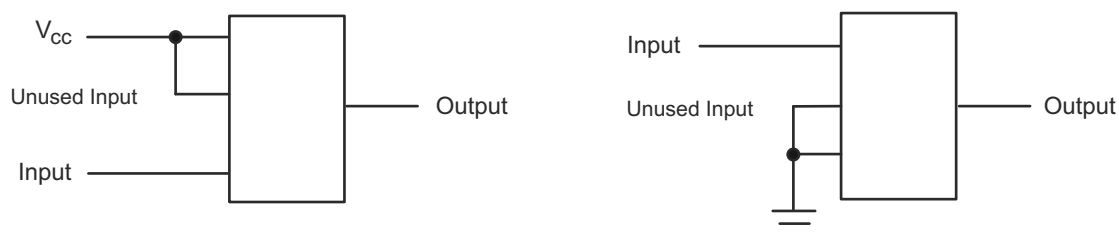


図 8-3. Layout Diagram

9 Device and Documentation Support

9.1 ドキュメントの更新通知を受け取る方法

ドキュメントの更新についての通知を受け取るには、www.tij.co.jp のデバイス製品フォルダを開いてください。
[通知] をクリックして登録すると、変更されたすべての製品情報に関するダイジェストを毎週受け取ることができます。変更の詳細については、改訂されたドキュメントに含まれている改訂履歴をご覧ください。

9.2 サポート・リソース

[テキサス・インスツルメンツ E2E™ サポート・フォーラム](#) は、エンジニアが検証済みの回答と設計に関するヒントをエキスパートから迅速かつ直接得ることができる場所です。既存の回答を検索したり、独自の質問をしたりすることで、設計に必要な支援を迅速に得ることができます。

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9.3 Trademarks

テキサス・インスツルメンツ E2E™ is a trademark of Texas Instruments.
すべての商標は、それぞれの所有者に帰属します。

9.4 静電気放電に関する注意事項



この IC は、ESD によって破損する可能性があります。テキサス・インスツルメンツは、IC を取り扱う際には常に適切な注意を払うことを推奨します。正しい取り扱いおよび設置手順に従わない場合、デバイスを破損するおそれがあります。

ESD による破損は、わずかな性能低下からデバイスの完全な故障まで多岐にわたります。精密な IC の場合、パラメータがわずかに変化するだけで公表されている仕様から外れる可能性があるため、破損が発生しやすくなっています。

9.5 用語集

[テキサス・インスツルメンツ用語集](#) この用語集には、用語や略語の一覧および定義が記載されています。

10 Revision History

資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

Changes from Revision P (April 2024) to Revision Q (July 2024)	Page
• Updated thermal values for PW package from RθJA = 103.3 to 116.8, RθJC(top) = 37.8 to 58.5, RθJB = 54.3 to 78.7, ΨJT = 2.9 to 12.6, ΨJB = 53.8 to 77.9, RθJC(bot) = N/A, all values in °C/W	5

Changes from Revision O (July 2014) to Revision P (April 2024)	Page
• Moved storage temperature from <i>Handling Ratings</i> table to <i>Absolute Maximum Ratings</i> table.....	4
• Changed Handling Ratings table to ESD Ratings table.....	4
• Added temperature range column labels in Electrical Characteristics table.....	5
• Added temperature range column labels in Timing Requirements table.....	5
• Changed t_{PLH} and t_{PHL} to be t_{pd} , t_{PZH} and t_{PZL} to be t_{en} , and t_{PLZ} and t_{PHZ} to be t_{dis}	6
• Changed <i>Switching Characteristics</i> table to be two tables separating military and catalog device characteristics.....	6
• Changed parameter measurement information section images and tables to improve clarity and update formatting.....	7

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
5962-9685501QRA	Active	Production	CDIP (J) 20	20 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9685501QR A SNJ54AHCT573J
5962-9685501QSA	Active	Production	CFP (W) 20	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9685501QS A SNJ54AHCT573W
SN74AHCT573DBR	Active	Production	SSOP (DB) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HB573
SN74AHCT573DBR.A	Active	Production	SSOP (DB) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HB573
SN74AHCT573DGSR	Active	Production	VSSOP (DGS) 20	5000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HB573
SN74AHCT573DGVR	Active	Production	TVSOP (DGV) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HB573
SN74AHCT573DGVR.A	Active	Production	TVSOP (DGV) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HB573
SN74AHCT573DWR	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	AHCT573
SN74AHCT573DWR.A	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	AHCT573
SN74AHCT573N	Active	Production	PDIP (N) 20	20 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 125	SN74AHCT573N
SN74AHCT573N.A	Active	Production	PDIP (N) 20	20 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 125	SN74AHCT573N
SN74AHCT573PW	Obsolete	Production	TSSOP (PW) 20	-	-	Call TI	Call TI	-40 to 125	HB573
SN74AHCT573PWR	Active	Production	TSSOP (PW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	(AHCT573, HB573)
SN74AHCT573PWR.A	Active	Production	TSSOP (PW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	(AHCT573, HB573)
SN74AHCT573PWRE4	Active	Production	TSSOP (PW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HB573
SN74AHCT573PWRG4	Active	Production	TSSOP (PW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HB573
SN74AHCT573PWRG4.A	Active	Production	TSSOP (PW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HB573
SN74AHCT573RKSR	Active	Production	VQFN (RKS) 20	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	AHCT573
SNJ54AHCT573J	Active	Production	CDIP (J) 20	20 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9685501QR A SNJ54AHCT573J
SNJ54AHCT573J.A	Active	Production	CDIP (J) 20	20 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9685501QR A SNJ54AHCT573J
SNJ54AHCT573W	Active	Production	CFP (W) 20	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9685501QS A SNJ54AHCT573W

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SNJ54AHCT573W.A	Active	Production	CFP (W) 20	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9685501QS A SNJ54AHCT573W

- (1) **Status:** For more details on status, see our [product life cycle](#).
- (2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.
- (3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.
- (4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.
- (5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.
- (6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54AHCT573, SN74AHCT573 :

- Catalog : [SN74AHCT573](#)
- Military : [SN54AHCT573](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AHCT573DBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74AHCT573DGSR	VSSOP	DGS	20	5000	330.0	16.4	5.4	5.4	1.45	8.0	16.0	Q1
SN74AHCT573DGVR	TVSOP	DGV	20	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74AHCT573DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74AHCT573PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.0	1.4	8.0	16.0	Q1
SN74AHCT573PWRG4	TSSOP	PW	20	2000	330.0	16.4	6.95	7.0	1.4	8.0	16.0	Q1
SN74AHCT573PWRG4	TSSOP	PW	20	2000	330.0	16.4	6.95	7.0	1.4	8.0	16.0	Q1
SN74AHCT573RKSR	VQFN	RKS	20	3000	180.0	12.4	2.8	4.8	1.2	4.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



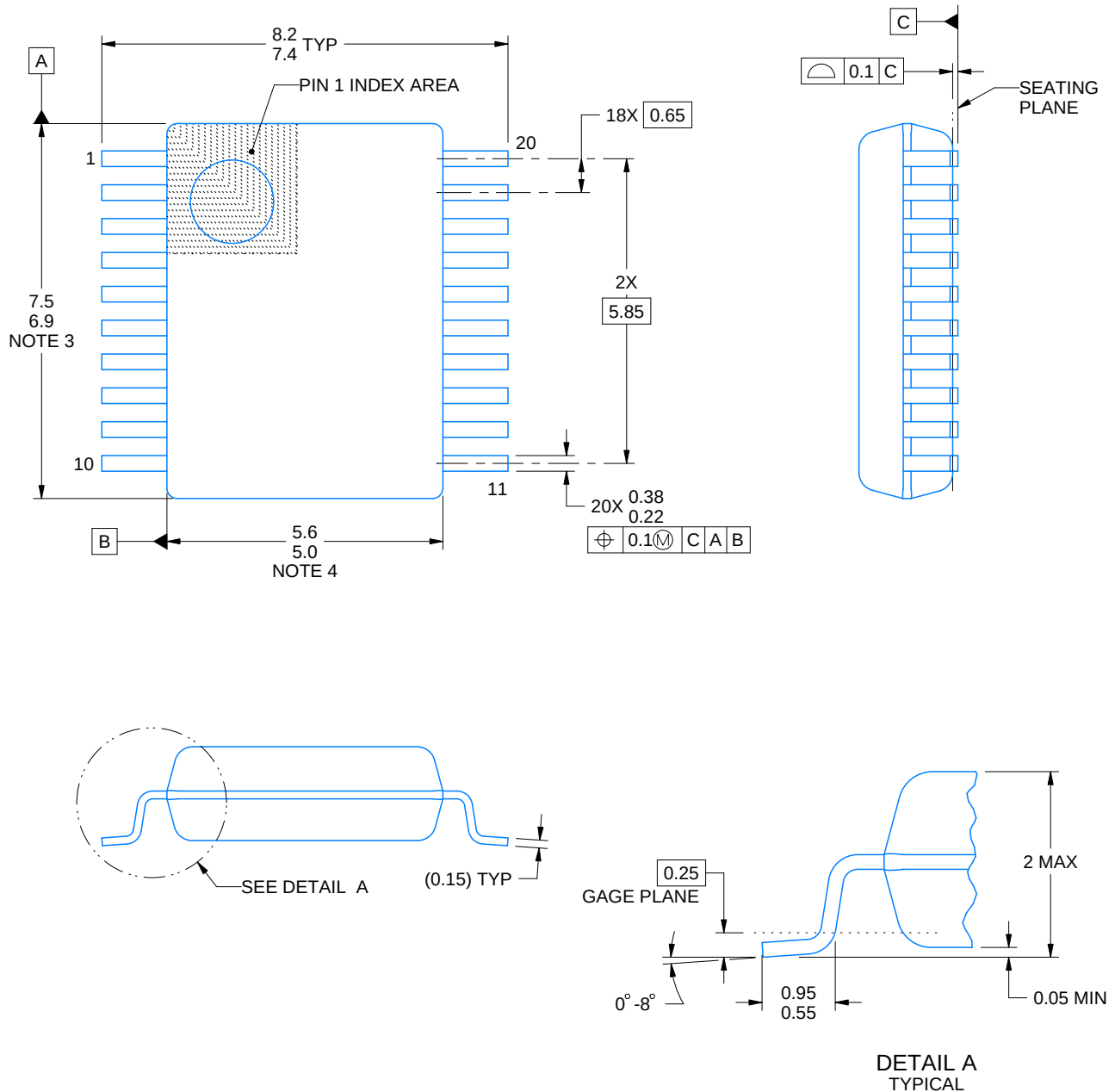
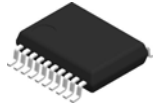
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AHCT573DBR	SSOP	DB	20	2000	353.0	353.0	32.0
SN74AHCT573DGSR	VSSOP	DGS	20	5000	353.0	353.0	32.0
SN74AHCT573DGVR	TVSOP	DGV	20	2000	353.0	353.0	32.0
SN74AHCT573DWR	SOIC	DW	20	2000	356.0	356.0	45.0
SN74AHCT573PWR	TSSOP	PW	20	2000	353.0	353.0	32.0
SN74AHCT573PWRG4	TSSOP	PW	20	2000	353.0	353.0	32.0
SN74AHCT573PWRG4	TSSOP	PW	20	2000	353.0	353.0	32.0
SN74AHCT573RKSR	VQFN	RKS	20	3000	210.0	185.0	35.0

TUBE


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
5962-9685501QSA	W	CFP	20	25	506.98	26.16	6220	NA
SN74AHCT573N	N	PDIP	20	20	506	13.97	11230	4.32
SN74AHCT573N.A	N	PDIP	20	20	506	13.97	11230	4.32
SNJ54AHCT573W	W	CFP	20	25	506.98	26.16	6220	NA
SNJ54AHCT573W.A	W	CFP	20	25	506.98	26.16	6220	NA



4214851/B 08/2019

NOTES:

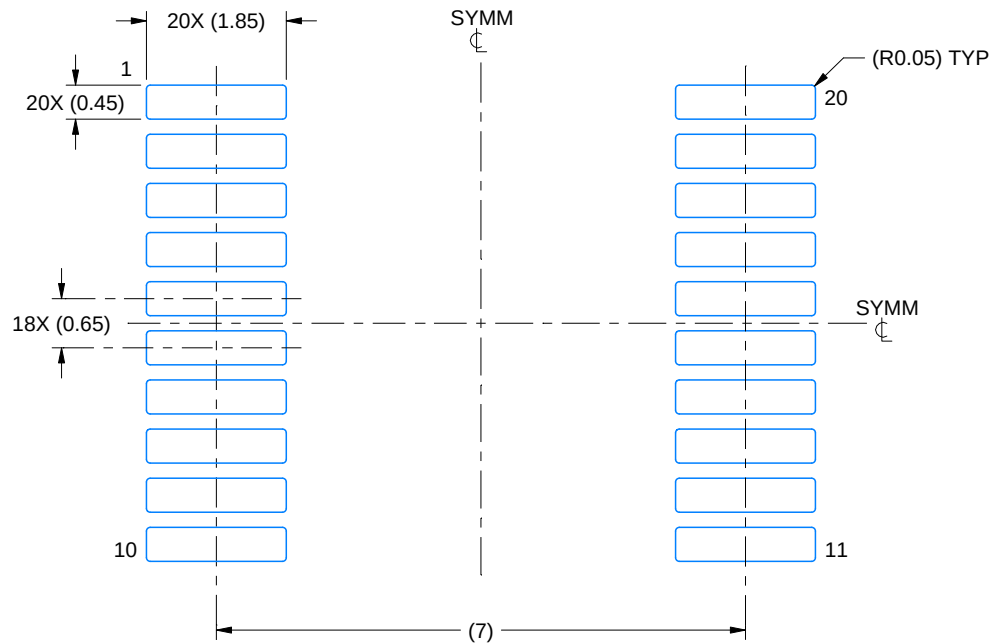
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-150.

EXAMPLE BOARD LAYOUT

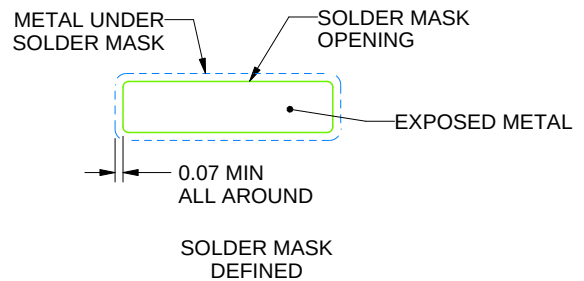
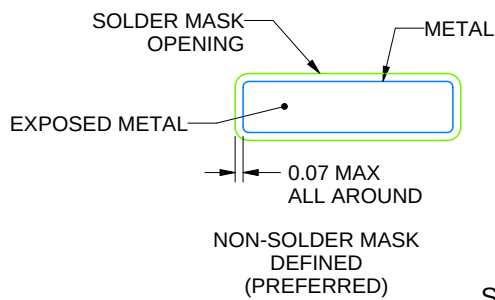
DB0020A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



SOLDER MASK DETAILS

4214851/B 08/2019

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

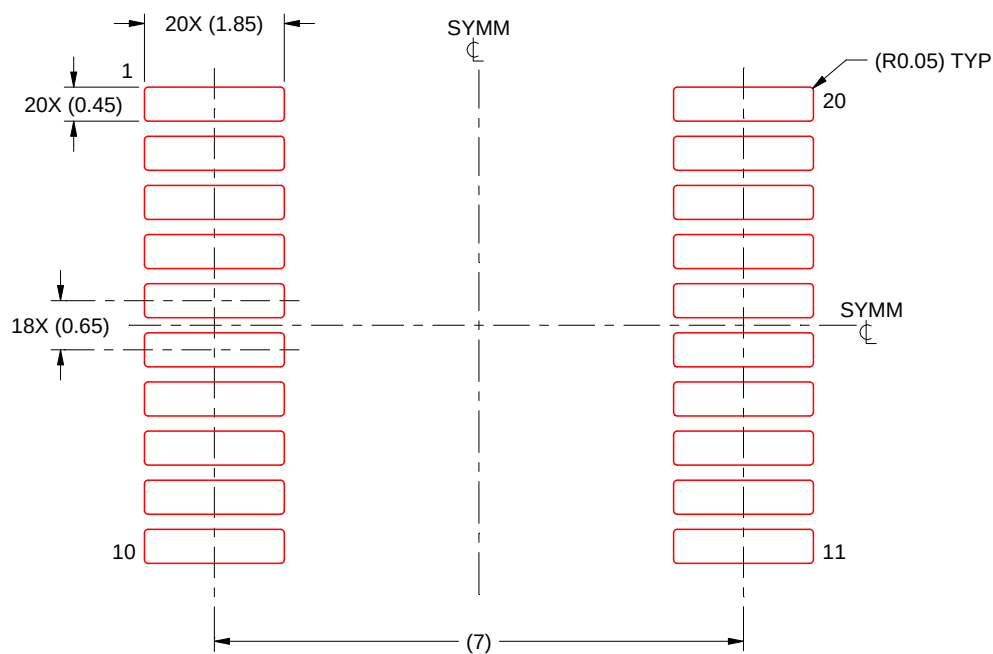
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DB0020A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4214851/B 08/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

GENERIC PACKAGE VIEW

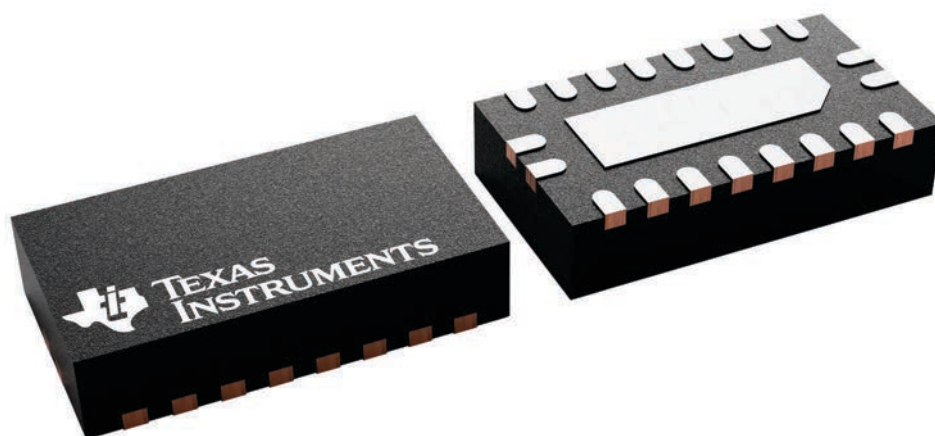
RKS 20

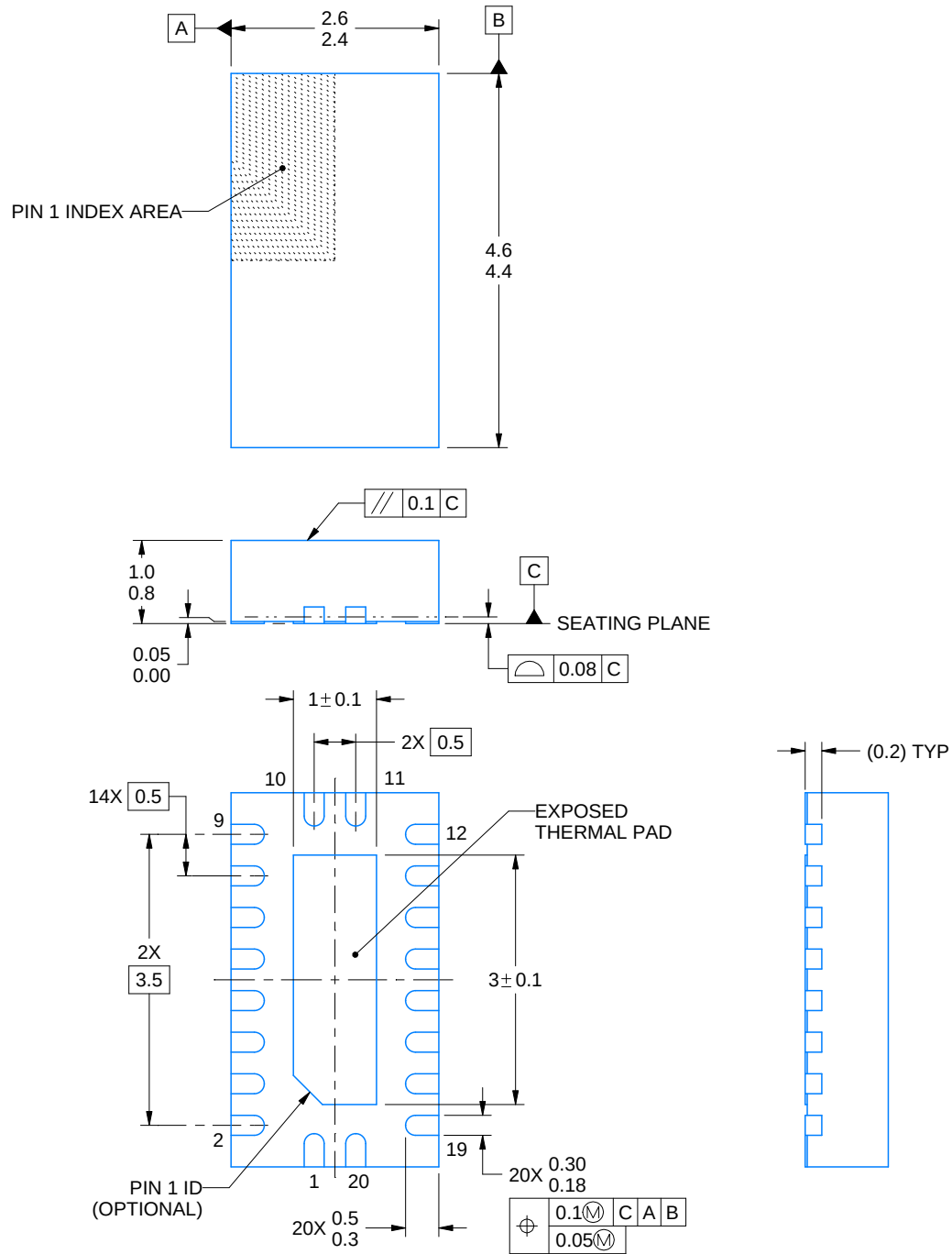
VQFN - 1 mm max height

2.5 x 4.5, 0.5 mm pitch

PLASTIC QUAD FLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.





4222490/B 02/2021

NOTES:

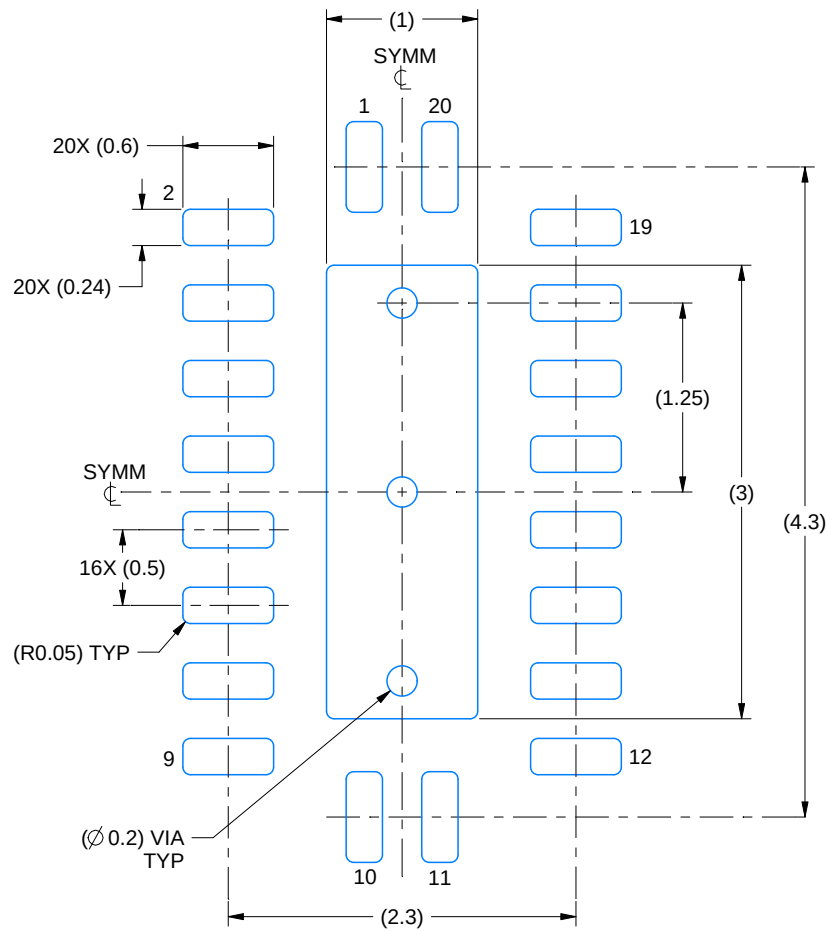
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

EXAMPLE BOARD LAYOUT

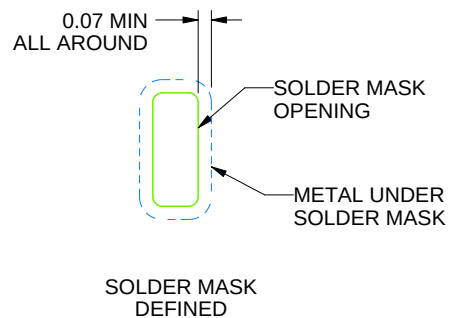
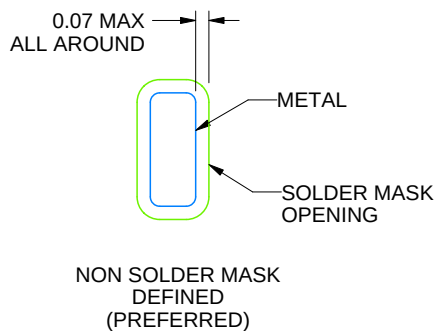
RKS0020A

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE
SCALE:20X



SOLDER MASK DETAILS

4222490/B 02/2021

NOTES: (continued)

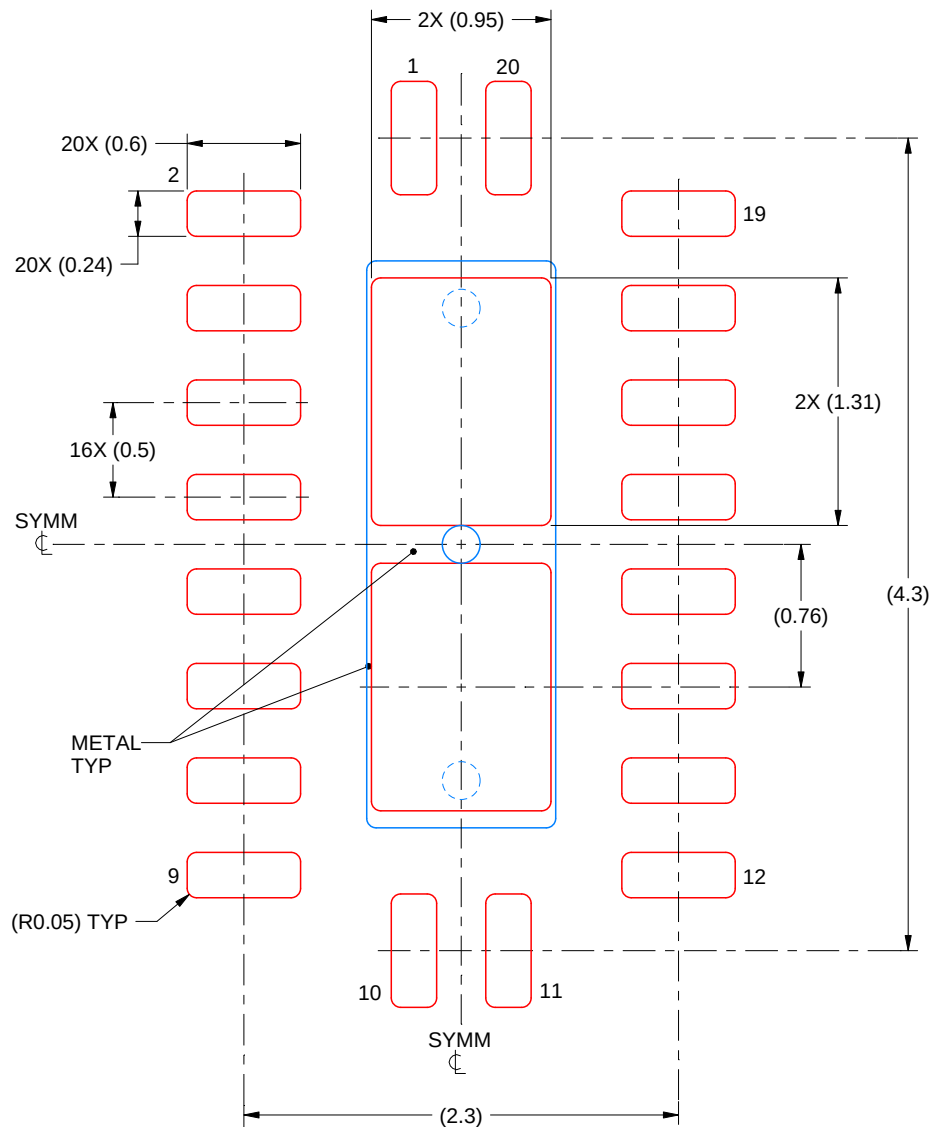
4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/sluea271).
5. Vias are optional depending on application, refer to device data sheet. If some or all are implemented, recommended via locations are shown.

EXAMPLE STENCIL DESIGN

RKS0020A

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



SOLDER PASTE EXAMPLE
 BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD
 83% PRINTED SOLDER COVERAGE BY AREA
 SCALE:25X

4222490/B 02/2021

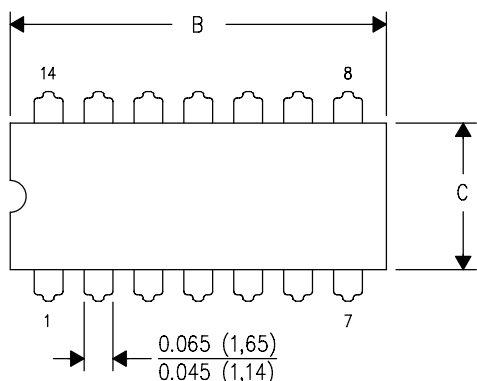
NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

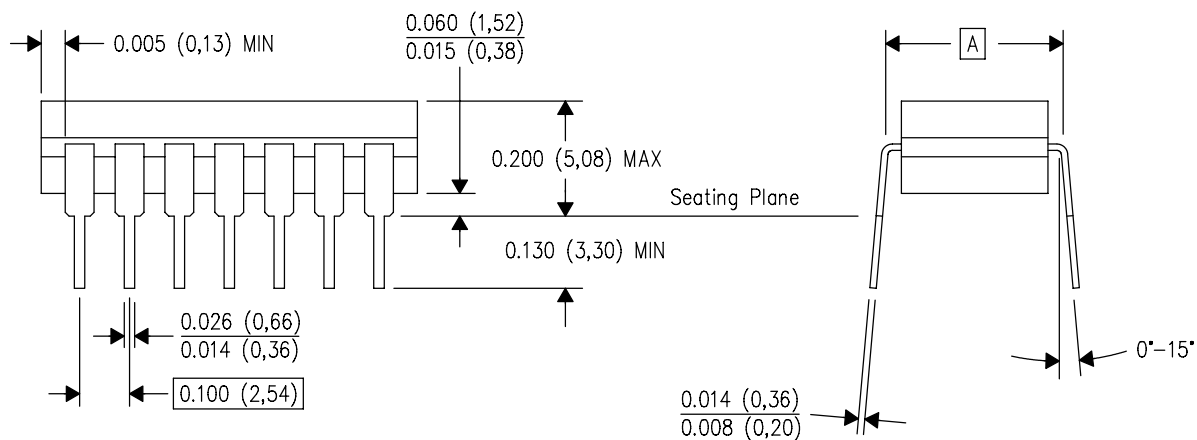
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



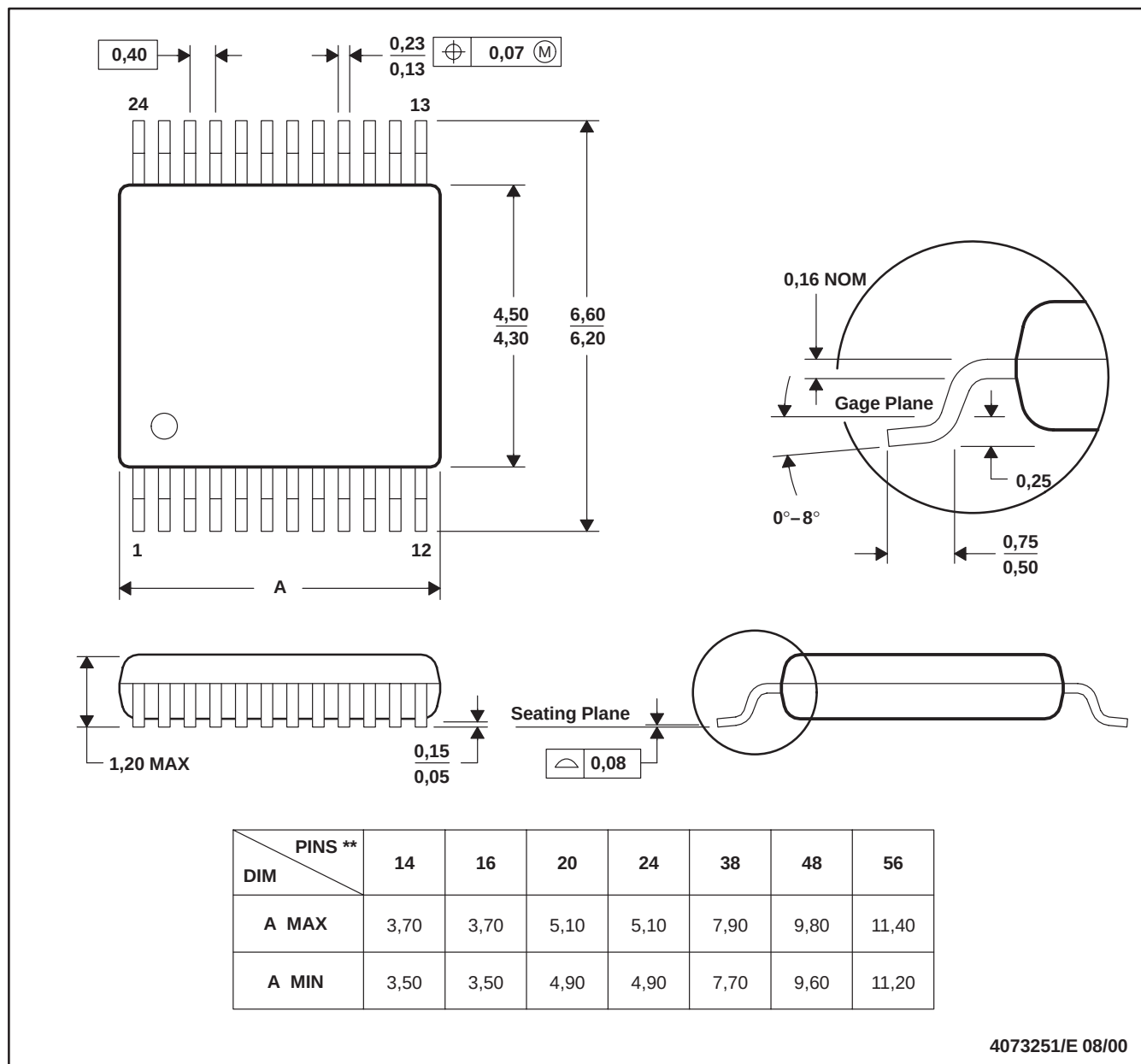
4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

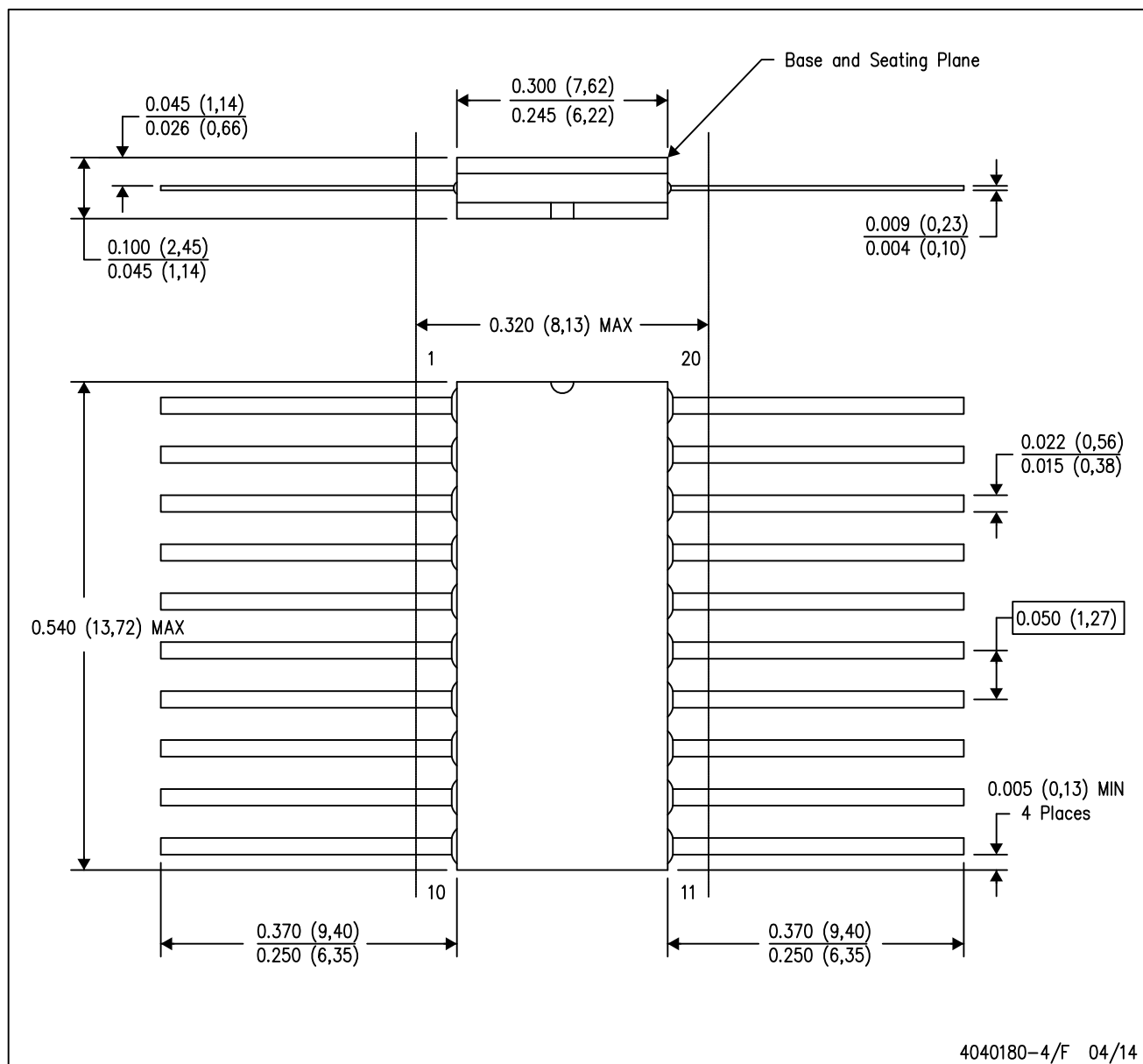
24 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



NOTES:

- All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- This package can be hermetically sealed with a ceramic lid using glass frit.
- Index point is provided on cap for terminal identification only.
- Falls within Mil-Std 1835 GDFP2-F20



TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE

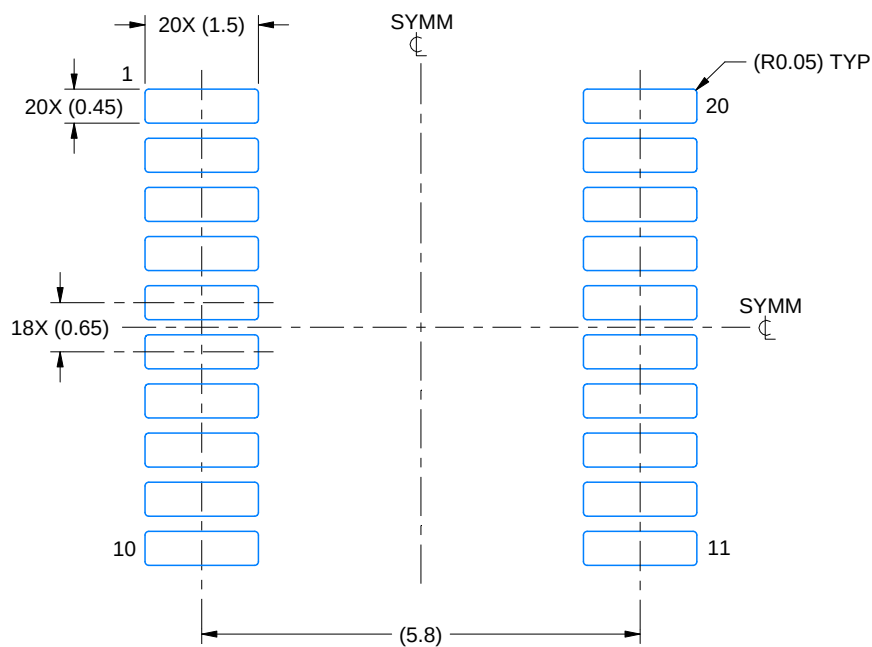


1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

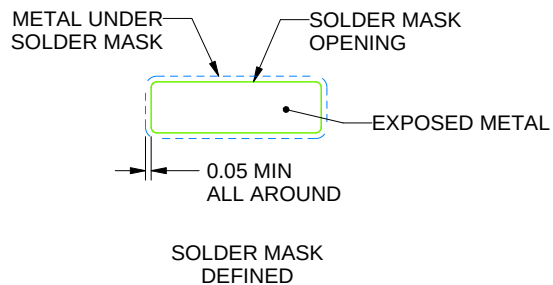
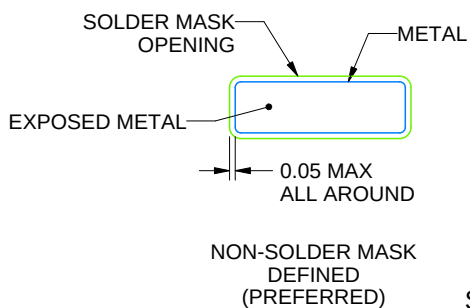
PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



SOLDER MASK DETAILS

4220206/A 02/2017

NOTES: (continued)

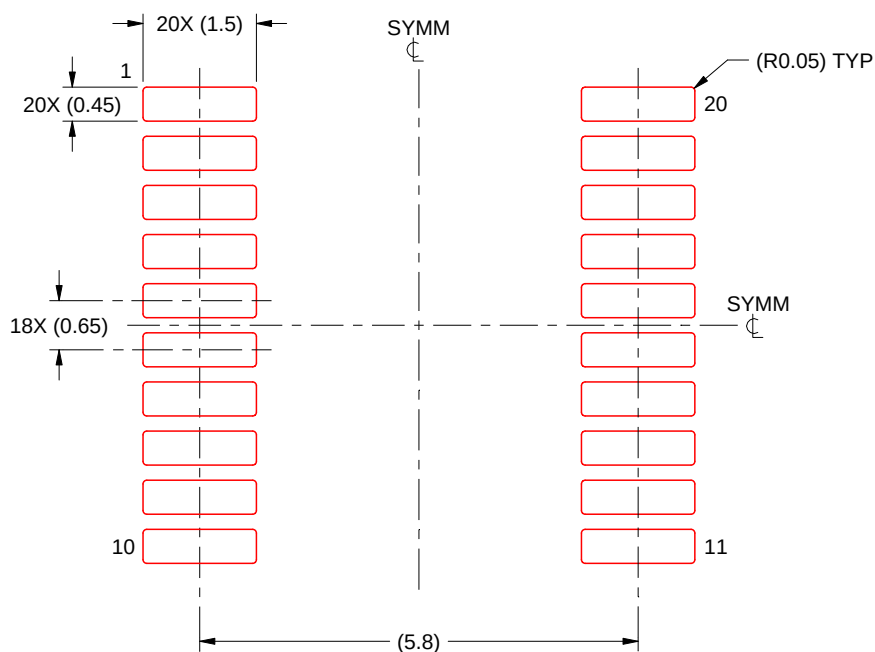
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE

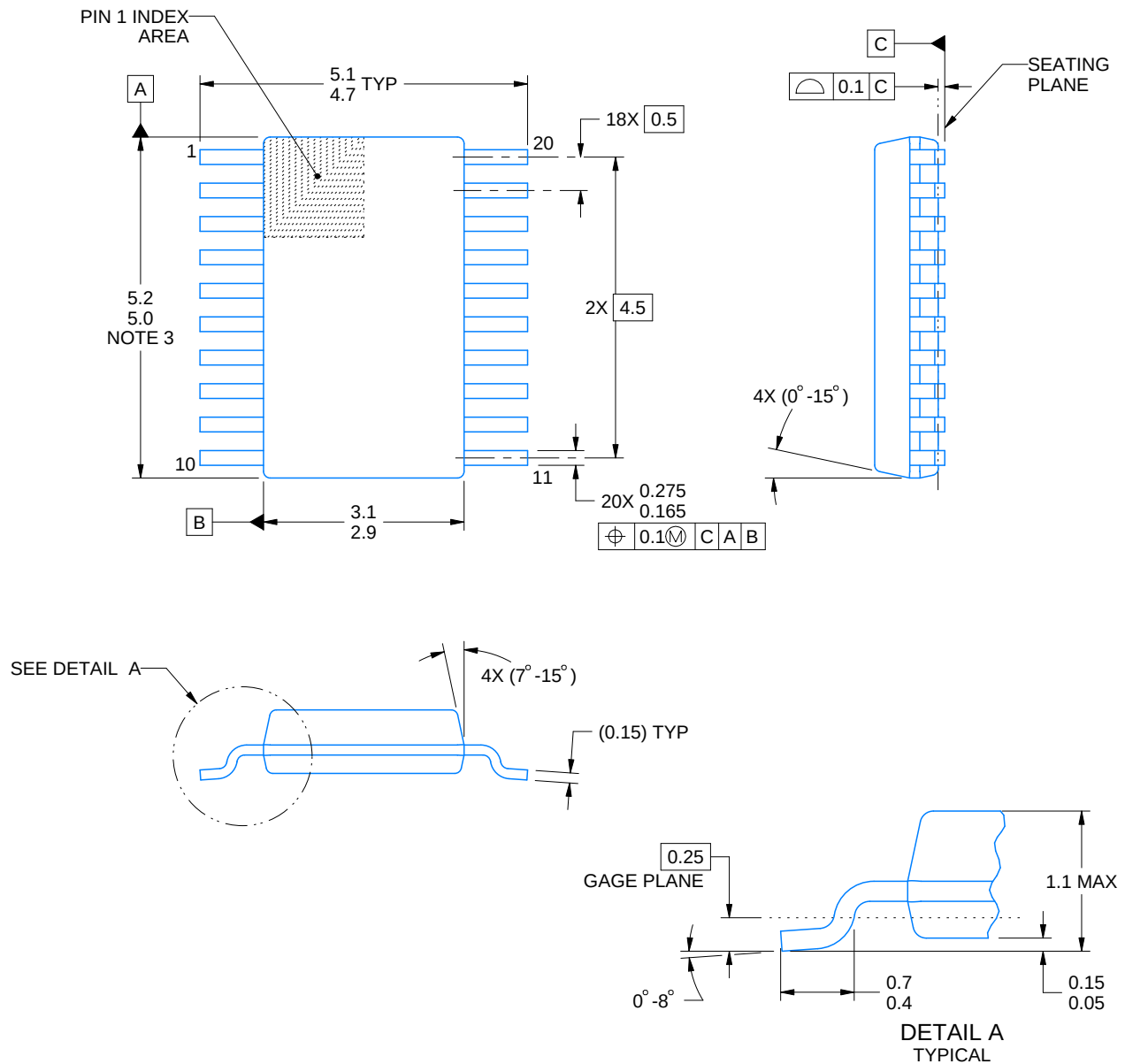


SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220206/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.



4226367/A 10/2020

NOTES:

PowerPAD is a trademark of Texas Instruments.

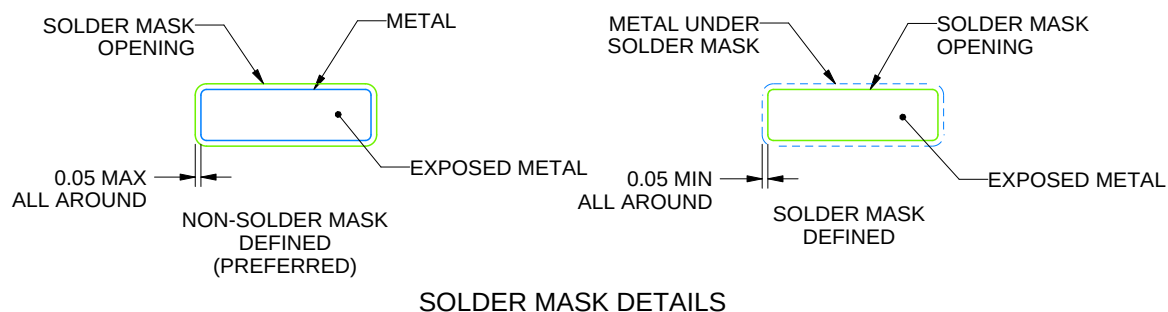
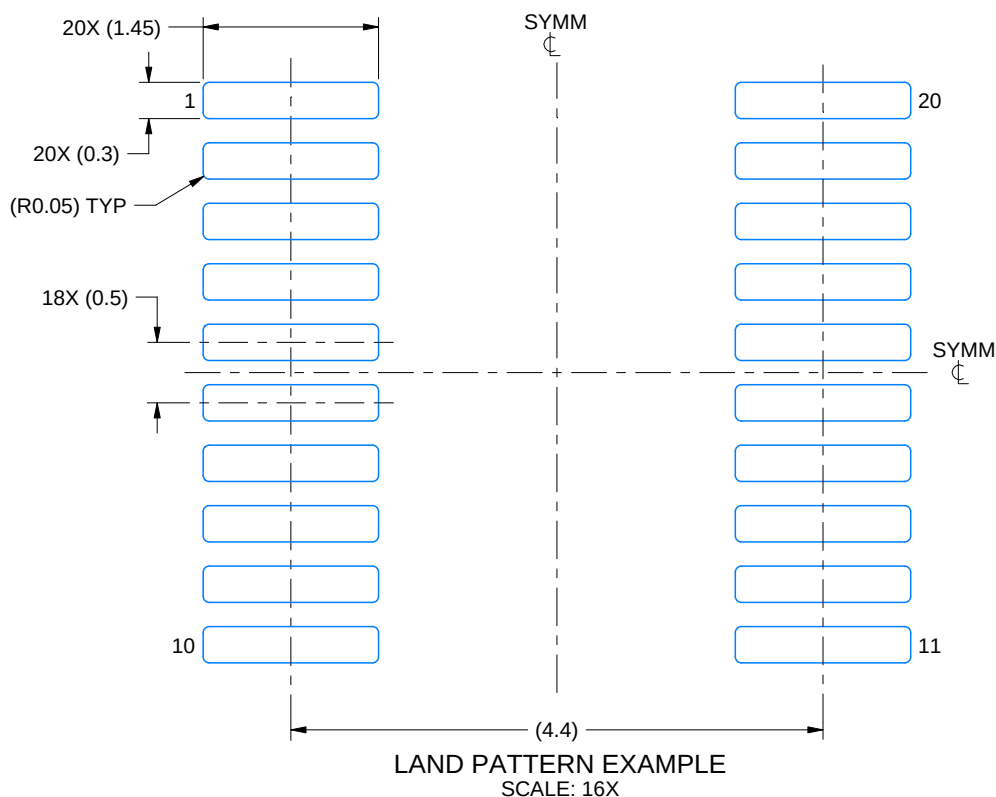
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. No JEDEC registration as of September 2020.
5. Features may differ or may not be present.

EXAMPLE BOARD LAYOUT

DGS0020A

VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



4226367/A 10/2020

NOTES: (continued)

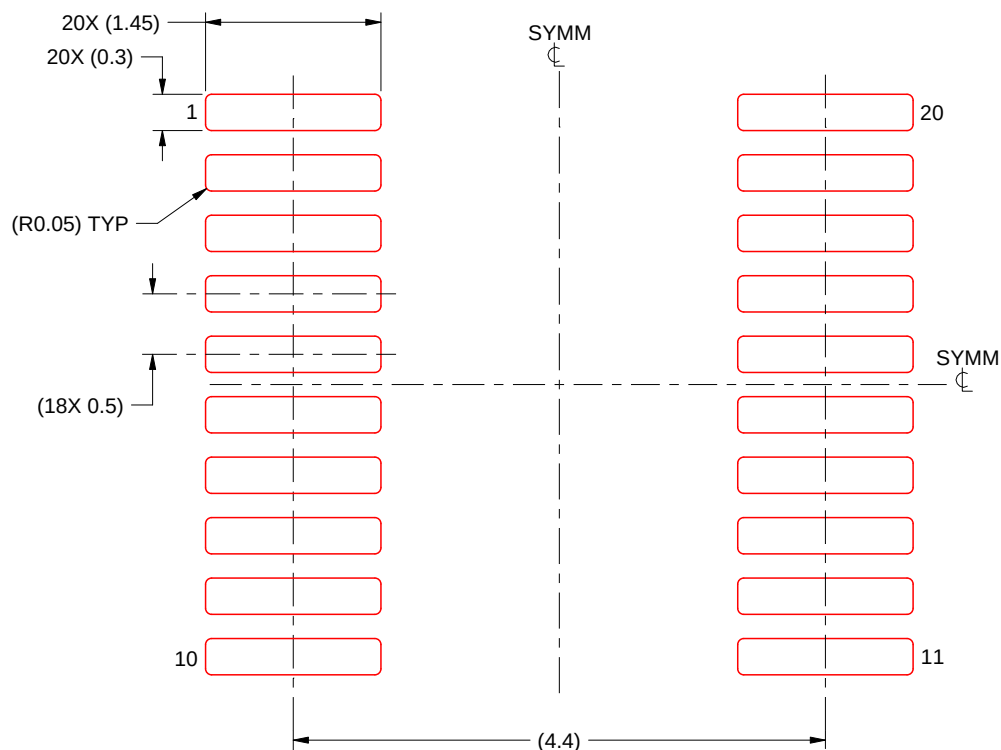
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
8. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature numbers SLMA002 (www.ti.com/lit/slma002) and SLMA004 (www.ti.com/lit/slma004).
9. Size of metal pad may vary due to creepage requirement.
10. Vias are optional depending on application, refer to device data sheet. It is recommended that vias under paste be filled, plugged or tented.

EXAMPLE STENCIL DESIGN

DGS0020A

VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 16X

4226367/A 10/2020

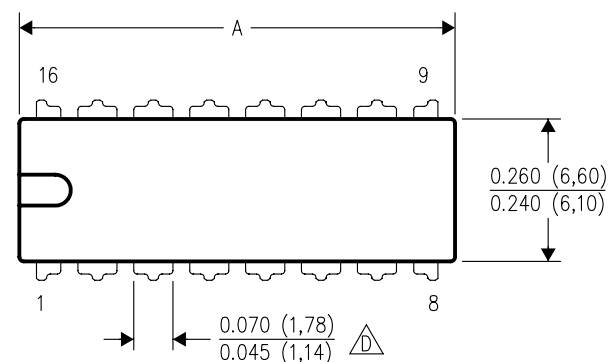
NOTES: (continued)

11. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
12. Board assembly site may have different recommendations for stencil design.

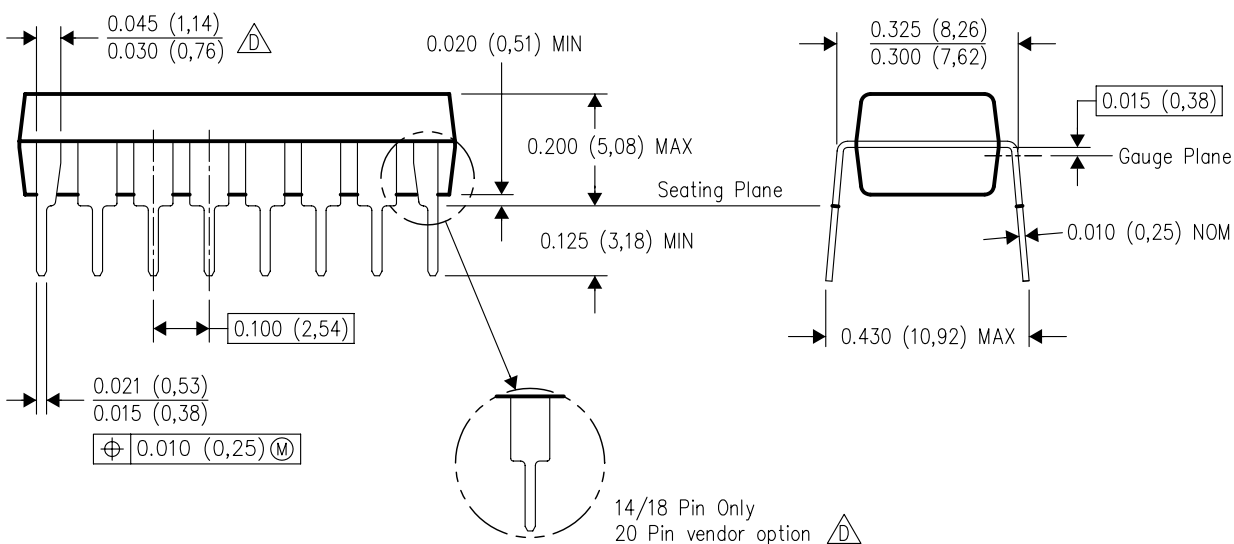
N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



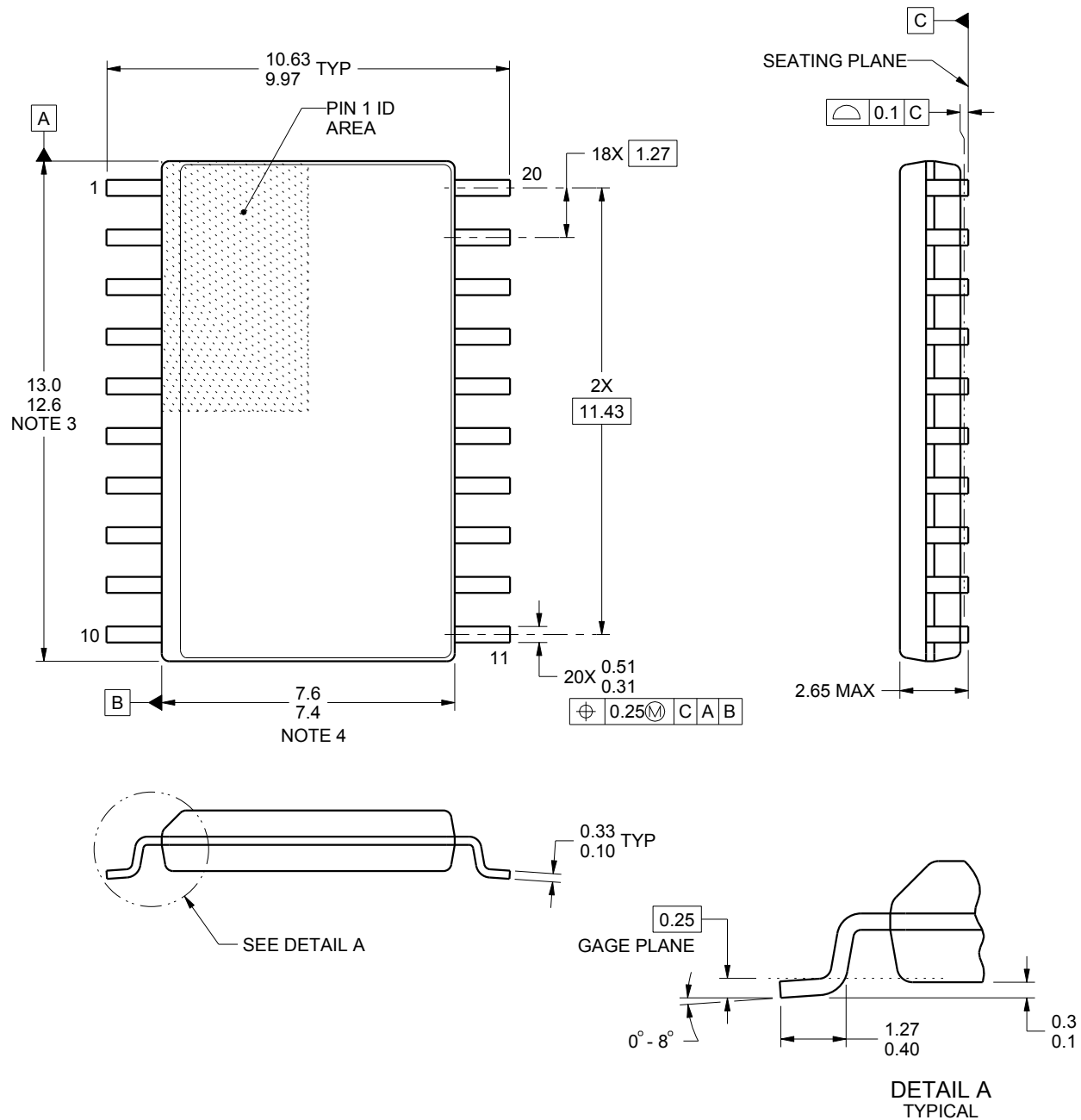
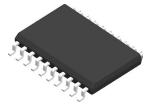
PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



4040049/E 12/2002

NOTES:

- A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
-  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 The 20 pin end lead shoulder width is a vendor option, either half or full width.



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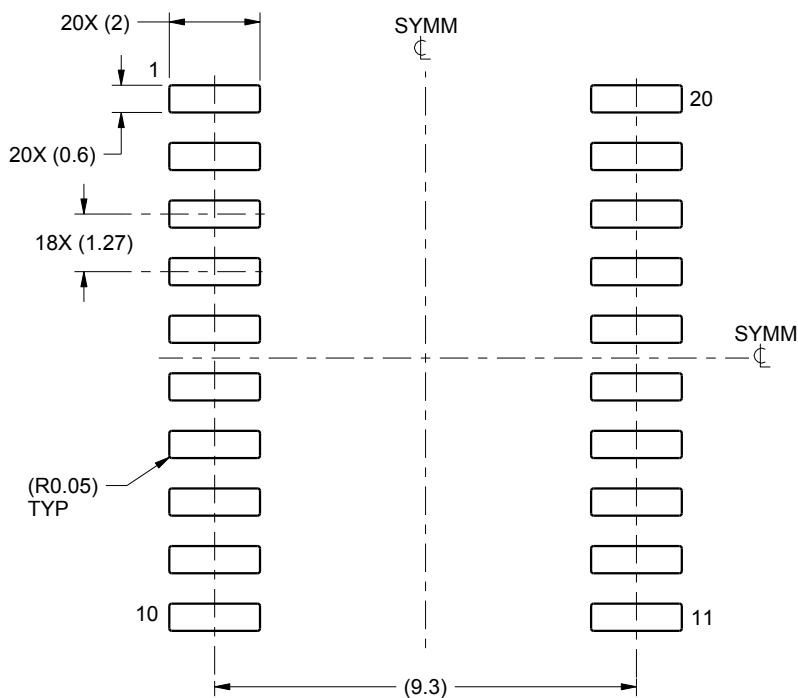
NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.

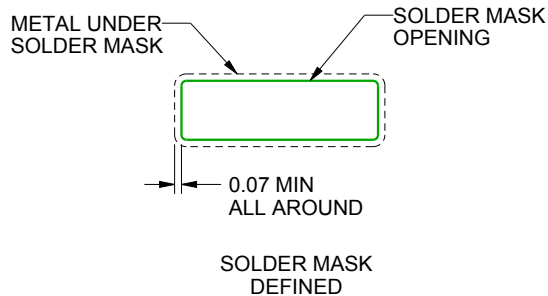
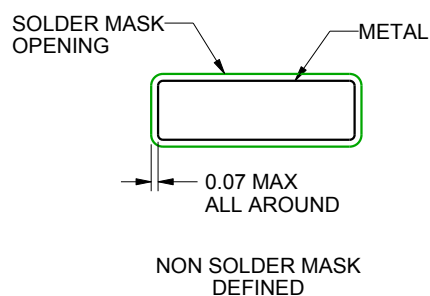
DW0020A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE
SCALE:6X



SOLDER MASK DETAILS

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NOTES: (continued)

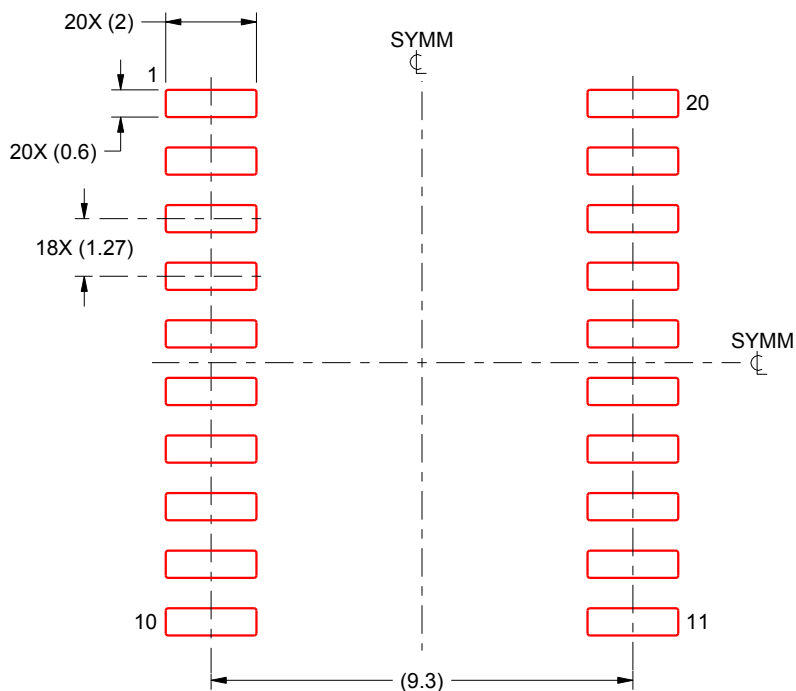
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

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NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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